



Material Content Data Sheet



Sales Product Name	TLE6711GL			Issued	1. August 2018			
MA#	MA001731842							
Package	PG-DSO-20-66			Weight*	486.95 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	6.251	1.28	1.28	12837	12837
leadframe	inorganic material	phosphorus	7723-14-0	0.039	0.01		80	
	non noble metal	zinc	7440-66-6	0.155	0.03		319	
	non noble metal	iron	7439-89-6	3.104	0.64		6375	
wire	non noble metal	copper	7440-50-8	126.041	25.88	26.56	258840	265614
	non noble metal	copper	7440-50-8	0.250	0.05	0.05	514	514
	encapsulation	organic material	carbon black	1333-86-4	0.689	0.14		1414
encapsulation	plastics	epoxy resin	-	31.677	6.51		65052	
	inorganic material	silicondioxide	60676-86-0	311.948	64.08	70.73	640619	707085
	leadfinish	non noble metal	tin	7440-31-5	2.746	0.56	0.56	5639
plating	noble metal	silver	7440-22-4	1.621	0.33	0.33	3330	3330
glue	plastics	epoxy resin	-	0.606	0.12		1245	
	noble metal	silver	7440-22-4	1.819	0.37	0.49	3736	4981
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com